

Application Of: Timothy W. Budell, Eric W. Tremble and Brian P. Welch
For: INTEGRATED CIRCUIT REDISTRIBUTION PACKAGE

Abstract

The present invention provides a redistribution package having an upper surface that includes contacts with reduced pitch that correspond, for example, to that of a Controlled Collapse Chip Connection (“C4”) structure formed on a chip, and a lower surface having contacts with increased pitch that correspond, for example, to a printed circuit board employing ball grid array (“BGA”) pads. A series of power, signal and ground conductors extend through the body of the redistribution package and interconnect the circuit board contacts to the chip contacts.